THE GUND COMPANY

MANUFACTURERS & FABRICATORS OF ENGINEERED MATERIAL SOLUTIONS

MPI - Mold Platen Insulation

Item:	**Mold Platen Insulation (MPI)**			
Description:	Mold Platen Insulation (MPI) from The Gund Company is a high compressive strength, heat resistant composite insulating material. It can be finished to close thickness tolerance, which makes it ideal for insulating between the mold and the press. The low thermal conductivity helps control mold temperature by reducing heat loss and allows for faster mold startup.			
Availability:	**Laminate Sheets:**		English Units (in)	SI Units (mm)
		Sheet Size:	36 x 72 / 48 x 96	914 x 1828 / 1219 x 2438
		Thickness:	0.031 - 2.000 / 0.118 - 1.500	0.78 - 50.8 / 3.0 - 38.1
	Fabricated Parts:	The Gund Company custom fabricates insulation materials to the exact specifications and drawings specified by our customers.		

Key Characteristics		Test Method	Units - English (SI)	Typical Values
Standard Color		--	--	Off White
Density		--	lbs/in^3 (g/cc)	0.071 (1.96)
IZOD Impact Strength	**Lengthwise**	ASTM D-256	ft-lbs/in	14.8
	Crosswise			13.4
Compressive Strength	**At Ambient Temperature**	ASTM D-695	psi (MPa)	49,000 (337)
	at 150 °C			30,000 (207)
	at 200 °C			23,000 (159)
	at 250 °C			20,000 (138)
Flexural Strength	**Lengthwise**	ASTM D-790	psi (MPa)	29,500 (200)
	Crosswise			24,500 (169)
Thermal Conductivity		ASTM C-177	Btu/hr/ft^2/in/°F (W/(m*K))	3.162 (0.456)
Water Absorption		ASTM D-570	%	0.12
Thickness Tolerance		--	in (mm)	0.003 (0.0762)
Tensile Strength		ASTM D-638	psi (MPa)	16,000 (110)
Dielectric Strength		ASTM D-149	V/mil (kV/mm)	450 (17.7)
Continuous Use Temperature		--	°F (°C)	428 (220)
Coefficient of Thermal Expansion		ASTM D-696	10^{-5}in/in/°F	1.25